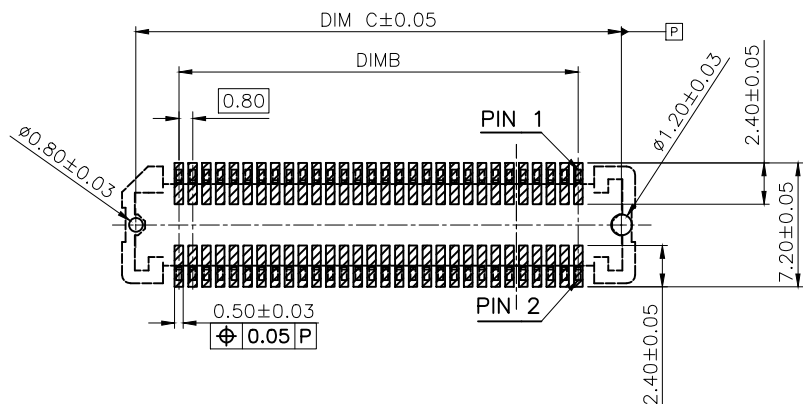
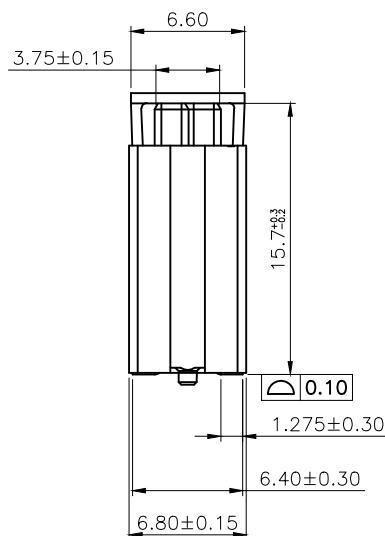
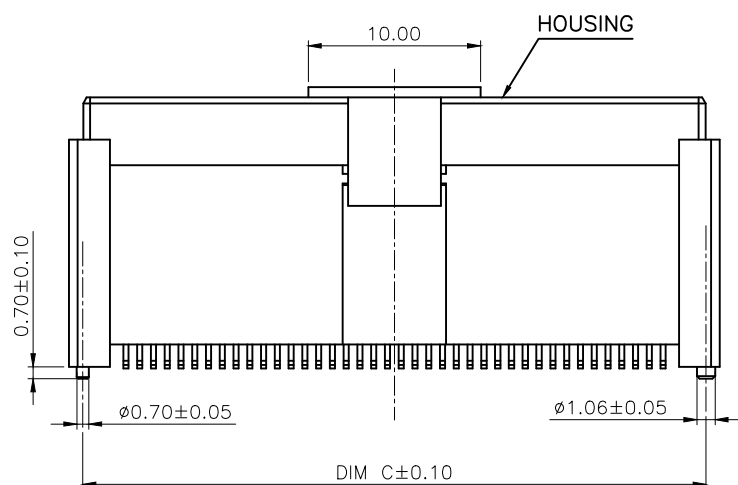
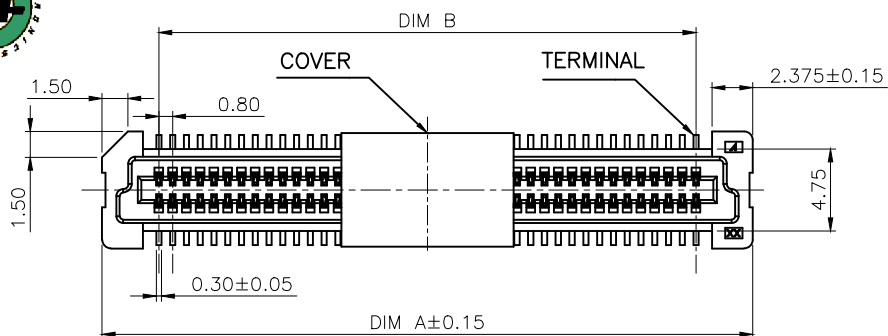
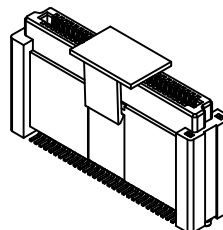




RECOMMEND PCB LAYOUT



NOTES:

1. MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0.
- 1.2 CONTACT: COPPER ALLOY.

2. FINISH:

2.1 CONTACT:

50~100u" NICKEL UNDERPLATING OVERALL.

1: GOLD FLASH ON CONTACT AND
60~150u" TIN ON SOLDER

G: 8u"MIN GOLD ON CONTACT AND
60~150u" TIN ON SOLDER

C: 15u"MIN GOLD ON CONTACT AND
60~150u" TIN ON SOLDER

3. REFLOW SOLDER CAPABLE TO 260°C
PER ACES SPEC.

4. SPEC.PLS REFER TO PS-51159-XXXXX-XXX

5. PACKAGE PLS REFER TO 51159-XXXXX-XX-TRP

6. PART NUMBER

51159-XXX X X-XXX

CKTS

XXX	HOUSING COLOR
001	NATURAL
002	BLACK

PLATING

1:GOLD FLASH ON CONTACT(LEAD FREE)

G:8u"MIN GOLD ON CONTACT(LEAD FREE)

C:15u"MIN GOLD ON CONTACT(LEAD FREE)

PACKING

7:TAPE REEL& WITH COVER

CKT	DIM A	DIM B	DIM C
40	21.80	15.20	20.20
60	29.80	23.20	28.20
80	37.80	31.20	36.20
100	45.80	39.20	44.20
120	53.80	47.20	52.20

QUALITY SYMBOLS

MAJOR

CRITICAL

GENERAL TOLERANCES (UNLESS SPECIFIED)

X. ±0.5

.X ±0.25

.XX ±0.15

.XXX ±0.1

ANGLES ±2°

DRAWN BY

Hu,Yang

CHECKED BY

BRAVE

APPROVED BY

BRAVE

UNITS

mm

SCALE

1:1

DATE

21/05/20

DATE

21/05/20

DATE

21/05/20

SIZE

A4

REV

B

ACES ELECTRONICS

0.8mm pitch BTB RECPT Conn.
SMT D/R S/T TYPE

RFQ NO.

N/A

PART NO.

SEE NOTES

DWG NO.

51159-XXXXX-XXX